

Please amend the present application as follows:

**Claims**

The following is a copy of Applicant's claims that identifies language being added with underlining ("\_\_\_\_") and language being deleted with strikethrough ("\_\_\_\_\_"), as is applicable:

1-16. (Canceled)

17. (Previously presented) A memory element comprising:  
a top conductor;  
a bottom conductor;  
an isolator element disposed between the top conductor and the bottom conductor,  
the isolator element being formed of a high-resistance conductor; and  
a non-conductive barrier layer disposed between the isolator element and the  
bottom conductor, the barrier layer being in contact with the bottom conductor;  
wherein the bottom conductor and the barrier layer each comprise a non-uniform  
surface.
18. (Previously presented) The memory element of claim 17, wherein the  
memory element comprises an anti-fuse element.
19. (Previously presented) The memory device of claim 17, wherein an  
average thickness of the barrier layer is between 10 and 30 angstroms.

20. (Previously presented) The memory device of claim 17, wherein the barrier layer has a dielectric breakdown voltage of between 2 and 3 volts.

21. (Previously presented) The memory element of claim 17, wherein the bottom conductor comprises a word line of a cross-point array of memory elements.

22. (Previously presented) The memory element of claim 21, wherein the barrier layer extends beyond the memory element along with the word line.

23. (Previously presented) The memory element of claim 17, wherein the bottom conductor is separate from a word line of a cross-point array of memory elements.

24-28. (Canceled)

29. (Previously presented) A memory element comprising:  
a top conductor;  
a bottom conductor;  
an isolator element disposed between the top conductor and the bottom conductor,  
the isolator element being formed as a p-n diode junction; and  
a non-conductive barrier layer disposed between the isolator element and the bottom conductor, the barrier layer being in contact with the bottom conductor;

wherein the bottom conductor and the barrier layer each comprise a non-uniform surface.

30. (Previously presented) The memory element of claim 29, wherein the memory element comprises an anti-fuse element.

31. (Previously presented) The memory device of claim 29, wherein an average thickness of the barrier layer is between 10 and 30 angstroms.

32. (Previously presented) The memory device of claim 29, wherein the barrier layer has a dielectric breakdown voltage of between 2 and 3 volts.

33. (Previously presented) The memory element of claim 29, wherein the bottom conductor comprises a word line of a cross-point array of memory elements.